

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	PARTIAL RELEASE OF GRANT OF SECURITY INTEREST - PATENTS										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Dymas Funding Company, LLC</td> <td>12/30/2011</td> </tr> </tbody> </table>		Name	Execution Date	Dymas Funding Company, LLC	12/30/2011						
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>Group Dekko, Inc.</td> </tr> <tr> <td>Street Address:</td> <td>2505 Dekko Drive</td> </tr> <tr> <td>City:</td> <td>Garrett</td> </tr> <tr> <td>State/Country:</td> <td>INDIANA</td> </tr> <tr> <td>Postal Code:</td> <td>46738</td> </tr> </table>		Name:	Group Dekko, Inc.	Street Address:	2505 Dekko Drive	City:	Garrett	State/Country:	INDIANA	Postal Code:	46738
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PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Patent Number:</td> <td>6796824</td> </tr> </tbody> </table>		Property Type	Number	Patent Number:	6796824						
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Patent Number:	6796824										
CORRESPONDENCE DATA											
Fax Number:	(212)593-5955										
Phone:	212-756-2132										
Email:	scott.kareff@srz.com										
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>											
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ATTORNEY DOCKET NUMBER:	018457-0015										
NAME OF SUBMITTER:	Scott Kareff (018457-0015)										
<p>Total Attachments: 3</p> <p>source=Partial Patent Release for Dymas Funding - Group Dekko#page1.tif</p> <p>source=Partial Patent Release for Dymas Funding - Group Dekko#page2.tif</p> <p>source=Partial Patent Release for Dymas Funding - Group Dekko#page3.tif</p>											

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PATENT

PARTIAL RELEASE OF GRANT OF A SECURITY INTEREST -- PATENTS

This PARTIAL RELEASE OF GRANT OF A SECURITY INTEREST -- PATENTS (the "Partial Release") is made and effective as of the date indicated below and is granted by Dymas Funding Company, LLC ("Releasor"), in favor of Group Dekko, Inc. ("Releasee").

WHEREAS, Releasee entered into the Amended and Restated Second Lien Credit Agreement, dated as of July 6, 2009 (as amended, restated, amended and restated, supplemented or otherwise modified from time to time, the "Credit Agreement"), among Releasee, the persons named therein as Loan Parties, the persons named therein as Lenders, and Releasor, as administrative agent for the Lenders providing, subject to the terms and conditions thereof, for certain Loans to be made available by the Lenders to Releasee from time to time;

WHEREAS, to induce Releasor and the Lenders to enter into the Credit Agreement with Releasee and to make Loans and other credit facilities available thereunder, Releasee executed and delivered a Patent Security Agreement, dated as of September 12, 2007 (the "Patent Security Agreement") whereby Releasee granted in favor of Releasor, as security for the Secured Obligations (as defined in the Patent Security Agreement), a security interest in, a general lien upon and/or a right of set-off against (whether then or thereafter owned by Releasee and whether acquired in the United States or elsewhere in the world) all right, title and interest of Releasee in and to the Collateral (as defined in the Patent Security Agreement) (the "Security Interest"), including the Released Patent (as defined below);

WHEREAS, the Patent Security Agreement was recorded at the United States Patent and Trademark Office at Reel 027074/Frame 0707 on October 10, 2011;

WHEREAS, Releasee has requested that Releasor release and discharge fully its Security Interest in and to the patent listed on **Schedule I** hereto, including all registrations and applications therefor and all rights associated therewith (the "Released Patent"); and

WHEREAS, Releasor is willing to release and discharge fully its Security Interest in and to the Released Patent.

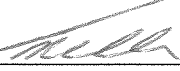
NOW, THEREFORE, in consideration of and in exchange for good and valuable consideration, Releasor hereby agrees as follows:

1. Defined Terms. All capitalized terms used but not otherwise defined herein have the meanings give to them in the Patent Security Agreement.
2. Partial Release of Patent Security Agreement. Releasor hereby, without any representation and warranty and without any recourse to Releasor, releases, relinquishes and discharges its Security Interest in and to the Released Patent. For the avoidance of doubt, Releasee acknowledges and agrees that this Partial Release does not release, relinquish or discharge Releasor's Security Interest in and to any Collateral (as defined in the Patent Security Agreement) other than the Released Patent.

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IN WITNESS WHEREOF, Releasor has caused this Partial Release to be duly executed by its officer thereunto duly authorized as of the 30th day of December 2011.

DYMAS FUNDING COMPANY, LLC

By: 

Name: Eric Miller

Title: Managing Director

SCHEDULE I

Released Patent

Title

Sealed IEC Electrical Connector Assembly

Patent No.

6,796,824

DOC ID-17791646.1